

L Number	Hits	Search Text	DB	Time stamp
1	34	(257/737 or 257/738) and (pad or contact\$2 or terminat\$2 or eletrode) with trapezoid\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/15 19:49
2	20	(257/739 or 257/778) and (pad or contact\$2 or terminat\$2 or eletrode) with trapezoid\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/15 19:50
3	21	(257/779 or 257/780) and (pad or contact\$2 or terminat\$2 or eletrode) with trapezoid\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/15 19:51
4	13	(257/781 or 257/782) and (pad or contact\$2 or terminat\$2 or eletrode) with trapezoid\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/15 19:51
5	26	(257/783 or 257/784) and (pad or contact\$2 or terminat\$2 or eletrode) with trapezoid\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/15 19:51
6	24	(257/785 or 257/786) and (pad or contact\$2 or terminat\$2 or eletrode) with trapezoid\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/15 19:52
-	490	(pad or contact\$2 or terminat\$2 or eletrode) with trapezoid	USPAT	2004/05/15 15:40
-	2456	(pad or contact\$2 or terminat\$2 or eletrode) with trapezoid\$3	USPAT	2004/05/15 19:42
-	490	(pad or contact\$2 or terminat\$2) with trapezoid	USPAT	2004/05/15 15:41
-	1	"08241940"	JPO	2004/05/15 19:42
-	13	6228466.pn. or 6573598.pn. or 6310304.pn. or 6310364.pn. or 6583445.pn. or 6653218.pn. or 6528874.pn. or 6495916.pn. or 6579739.pn. or 5388577.pn. or 6387793.pn. or 6228466.pn. or 6198169.pn. or 6104201.pn.	USPAT; JPO	2004/05/15 16:04
-	14	6228466.pn. or 6573598.pn. or 6310304.pn. or 6310364.pn. or 6583445.pn. or 6653218.pn. or 6528874.pn. or 6495916.pn. or 6579739.pn. or 5388577.pn. or 6387793.pn. or 6228466.pn. or 6198169.pn. or 6104201.pn. or 5609704.pn.	USPAT; JPO	2004/05/15 16:04
-	2	((pad or contact\$2 or terminat\$2 or eletrode) with trapezoid\$3) and (semiconductor or die or chip or IC)) and (pad or contact\$2 or terminat\$2 or eletrode) with trapezoid\$3 same (coat\$3 or plat\$3) near (layer or film)	USPAT	2004/05/15 16:19
-	632	((pad or contact\$2 or terminat\$2 or eletrode) with trapezoid\$3) and (semiconductor or die or chip or IC)	USPAT	2004/05/15 16:11
-	1		USPAT	2004/05/15 16:13
-	1		USPAT	2004/05/15 16:13
-	1		USPAT	2004/05/15 16:13
-	73	257/779 and (pad or contact\$2 or terminat\$2 or eletrode) with (coat\$3 or plat\$3) near (layer or film)	USPAT	2004/05/15 16:50
-	100	257/780 and (pad or contact\$2 or terminat\$2 or eletrode) with (coat\$3 or plat\$3) near (layer or film)	USPAT	2004/05/15 16:48

-	68	(257/780 and (pad or contact\$2 or terminat\$2 or eletrode) with (coat\$3 or plat\$3) near (layer or film)) not (257/779 and (pad or contact\$2 or terminat\$2 or eletrode) with (coat\$3 or plat\$3) near (layer or film))	USPAT	2004/05/15 16:44
-	4817	(semiconductor or die or chip or IC) and (pad or contact\$2 or terminat\$2 or eletrode) with (coat\$3 or plat\$3) near (layer or film)	USPAT	2004/05/15 16:49
-	23	(semiconductor or die or chip or IC) and (pad or contact\$2 or terminat\$2 or eletrode) with (coat\$3 or plat\$3) near (layer or film) with upper near portion	USPAT	2004/05/15 16:50
-	1261	257/779	USPAT	2004/05/15 16:51